RUGGED GROUND PLANE
Q2™ HIGH-SPEED INTERCONNECTS

- Integral power/ground plane rated up to 17.7 A
- 0.635 mm pitch
- Increased insertion depth for rugged applications
- Up to 156 signal pins/48 differential pairs standard
- Shielding available for EMI protection
- 10 – 16 mm stack heights
- Optional guide posts
- Meets PCI/104-Express™ standard specifications
- Standoffs available to aid with unmating and protect from damage (SO Series)

**INTEGRAL GROUND PLANE**
- Surface mount ground plane between two signal rows improves electrical performance
- Significantly reduces row-to-row crosstalk
- Reduces coupling between pins within a row

**SYSTEM**
- **QMS** – 0.635 mm Ground Plane Header
- **QFS** – 0.635 mm Ground Plane Socket
- **QMSS** – 0.635 mm Shielded Ground Plane Header
- **QFSS** – 0.635 mm Shielded Ground Plane Socket

Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

For more High-Speed Board-to-Board Solutions, please visit samtec.com/mezzanine